

TO: _____

Subject: Notification of an additional backend site of Memory Products

Toshiba would like to notify you about an additional Backend Site of Memory Products.

1. APPLICABLE PRODUCTS

24nm SLC NAND BGA(9x11mm) Package Products

| | Density | 3.3V | 1.8V |
|---------|---------|-----------------|-----------------|
| RawNAND | 1Gb | TC58NVG0S3HBAI4 | TC58NYG0S3HBAI4 |
| | 2Gb | TC58NVG1S3HBAI4 | TC58NYG1S3HBAI4 |
| | 4Gb | TC58NVG2S0HBAI4 | TC58NYG2S0HBAI4 |
| BENAND | 1Gb | TC58BVG0S3HBAI4 | TC58BYG0S3HBAI4 |
| | 2Gb | TC58BVG1S3HBAI4 | TC58BYG1S3HBAI4 |
| | 4Gb | TC58BVG2S0HBAI4 | TC58BYG2S0HBAI4 |

2. REASON OF CHANGE & CONTENT

To increase the production capacity and flexibility, we would like to introduce a new assembly site, Powertech Technology Inc. (PTI) in Taiwan, in addition to Amkor Shanghai in China. The material will be changed at new assembly site.

3. IMPLEMENTATION DATE

It will be added from Feb. 2017.

4. RELIABILITY DATA:

| | |
|---|---------------------------|
| (1) Adhesive Test | Available date: Dec. 2016 |
| (2) Temperature Cycling Test (TCT) | Available date: Jan. 2017 |
| (3) Highly Accelerated Stress Test (HAST) | Available date: Dec. 2016 |

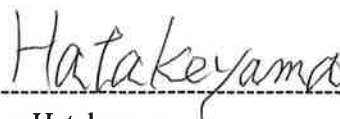
5. IDENTIFICATION OF PRODUCTS

The difference of backend sites can be identified by product origin, control code on the package surface and the 1st alphabet of the additional (ADD) code on the packing label.

| | Assembly/Test Site | Product Origin | Control Code | ADD Code |
|---------------|--------------------|----------------|--------------|----------|
| Current | Amkor Shanghai | CHINA | KLE | J## |
| New(Addition) | (PTI) | TAIWAN | 9AE | B## |

If you have any inquiry on this subject, please contact our sales department.

Sincerely yours,



Kazuo Hatakeyama
Group Manager
Memory Customer Quality Engineering Group
Memory Q & R Engineering Department
Toshiba corp. Storage & Electronic Devices Solutions Co.